Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of manufacturing a semiconductor device comprising: ~~a step of~~ preparing a wiring substrate having a base substrate on which are formed interconnecting lines;

mounting a semiconductor chip on ~~a wiring substrate having a~~ the base ~~substrate on which are formed interconnecting lines,~~substrate;

~~wherein while~~ melting the base substrate, while bumps ~~provided to~~provided on the semiconductor chip are pressed ~~in~~into the base substrate;~~,~~ and ~~the bumps are~~ electrically ~~connected~~ connecting the bumps to the interconnecting lines.

2. (Currently Amended) The method of manufacturing a semiconductor device as defined in claim 1,

wherein the interconnecting lines comprise connecting portions electrically connecting with the bumps, and

wherein in the step of electrical connection, the base substrate is melted, ~~and~~ so that connections of the bumps and the connecting portions are sealed with the melted material of the base substrate.

3. (Currently Amended) The method of manufacturing a semiconductor device as defined in claim 1,

wherein ~~in the step of electrical connection, the base substrate is melted, and~~ the melted material of the base substrate is adhered closely to a surface of the semiconductor chip.

4.. (Original) The method of manufacturing a semiconductor device as defined in claim 1,

wherein in the step of electrical connection, the base substrate is melted by heat.

5. (Original) The method of manufacturing a semiconductor device as defined in claim 1,

wherein a thermoplastic resin is used as the base substrate.

6. (Original) The method of manufacturing a semiconductor device as defined in claim 1, Jig for Insert

wherein in the step of electrical connection, the semiconductor chip is held by a jig, heat is applied to the jig to heat at least the bumps of the semiconductor chip, and the jig is pressed in the direction of the base substrate, whereby the bumps are pressed into the base substrate.

7. (Currently Amended) The method of manufacturing a semiconductor device as defined in claim 1, further comprising:

~~a step of~~ mounting another semiconductor chip on the wiring substrate.

8. (Withdrawn) A semiconductor device manufactured by the manufacturing method as defined in claim 1.

9. (Withdrawn) A semiconductor device comprising:

a semiconductor chip having electrodes on which bumps are formed; and

a wiring substrate on which the semiconductor chip is mounted, and having a base substrate on which are formed interconnecting lines having connecting portions electrically connecting to the bumps,

wherein the bumps are embedded in the base substrate and electrically connected to the interconnecting lines; and

wherein the bumps and the connecting portions are sealed by the base substrate.

10. (Withdrawn) The semiconductor device as defined in claim 9, wherein the base substrate is adhered closely to a surface of the semiconductor chip.

11. (Withdrawn) The semiconductor device as defined in claim 9, wherein the base substrate is a thermoplastic resin.

12. (Withdrawn) The semiconductor device as defined in claim 9, further comprising:

another semiconductor chip mounted on the wiring substrate.

13. (Withdrawn) A circuit board on which the semiconductor device as defined in claim 8 is mounted.

14. (Withdrawn) A circuit board on which the semiconductor device as defined in claim 9 is mounted.

15. (Withdrawn) An electronic instrument comprising the semiconductor device as defined in claim 8.

16. (Withdrawn) An electronic instrument comprising the semiconductor device as defined in claim 9.

17. (New) The method of manufacturing a semiconductor device as defined in claim 1,

wherein in the step of mounting the semiconductor chip, the bumps are contacted on a surface of the base substrate.

18. (New) A method of manufacturing a semiconductor device including a step of mounting a semiconductor chip on a wiring substrate having a base substrate on which are formed interconnecting lines, the method comprising:

mounting the semiconductor chip on the base substrate so that a surface of the base substrate opposite to the surface on which the interconnecting lines are formed is in contact with bumps formed on the semiconductor chip; and

electrically connecting the bumps to the interconnecting lines by heating at least the bumps and pressing the semiconductor chip toward the base substrate so that the base substrate is melted and the bumps are pushed into the base substrate.